Plating

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Process Technology

- Electro DeFlash / Electro Plating/ solder plating. 150 - 1000 bar low to high pressure for small/big packages

State of Art Machine & Process

- Capable of handling any leadframe product up to 110 x 315 mm.
- Uses an endless carrier belt to transport leadframes through various processing stages, ensuring consistent quality. Specially designed to hold leadframes in mechanical and electrical contact.
- The continuous processing ensures that each leadframe experiences the same plating conditions, resulting in consistent quality. Recipe-controlled.
- Integrated switches to stop production and trigger alarms if levels are too low1.
- Transports leadframes at speeds up to 8 meters per minute.
- Height Adjustable Overflows: Plating sections have height adjustable lengthwise overflows.
- Polypropylene: Used in electro-chemical, chemical, rinse, and drag-out sections.
- Batch Control: Ensures no inter-mixing between leadframes from different cassettes.

SUCHI SEMICON